

**Abstract**

The invention relates to a arrangement for increasing the packing density on a printed circuit (1) with surface mounted electrical components (2), with the printed circuit (1) being formed by two films (3x, 3y) which are pressed against one another with a dielectric (4) arranged between them, and with at least one of the mutually opposite faces (3a, 3b) of the films (3x, 3y) being fitted with surface mounted electrical components (2). According to the invention, via holes (6b) are provided in the printed circuit (1) in order to connect the two films (3x, 3y), with each via hole (6b) being a direct connection between the mutually opposite faces (3a, 3b) of the films (3x, 3y).

(Figure 3)